

Future of Computing

Superconducting Quantum Chips as the Foundation for Quantum Computing

J. Hassel
VP of Quantum Technologies
IQM Quantum Computers, Espoo, Finland

Abstract

Quantum computing based on superconducting chips is currently one of the most promising approaches for industrially relevant quantum computing. In this presentation, we will review IQM's comprehensive approach to quantum computing, spanning from chip design to full-scale systems, and showcase exemplary computing applications that are enabled by today's quantum computers. We will highlight the key aspects related to superconducting quantum chips, including the specific requirements and solutions for maintaining quantum coherence. Additionally, we will provide an overview of IQM's chip fabrication capabilities and how they align with the company's vision for scaled-up, future systems that will be necessary for fault-tolerant quantum computing. We will also present key performance metrics for our chips, including T1 coherence times of up to nearly one millisecond and 2-qubit gate fidelities of up to 99.93%, which have been achieved using IQM's tunable coupler approach. Furthermore, we will deliver a status update on the development of our full Quantum Processing Units (QPUs), featuring our current-generation chips with up to 54 and 150 qubits. Finally, we will outline IQM's scaling roadmap towards fault-tolerant quantum computing.

Biography

Dr. Juha Hassel received his PhD title in 2004 from Helsinki University of Technology (now Aalto University). As of March 2024, he holds the position of Vice President of Quantum Technologies at IQM Quantum Computers, where he has worked in different leadership positions since 2019. Before joining IQM, he served as Principal Scientist at VTT Technical Research Centre of Finland, where he also led the Applied Quantum Electronics team within the national Centre of Excellence – Quantum Technology Finland.

References

Photonic Integrated Circuits for LiDAR: Enabling 4D Machine Vision with PICs

R. Nicolaescu
Managing Director
Pointcloud, Zurich, Switzerland



Abstract

Detailed and accurate three dimensional (3D) mapping of dynamic environments is essential for machines to interact with their surroundings, and for human machine interaction. While considerable effort has been spent in order to create the equivalent of the CMOS image sensor for the 3D world, scalable, high performance, reliable solutions have proven elusive. Focal plane array (FPA) sensors using frequency modulation (FM) light detection and ranging (LiDAR) have shown potential to meet all the requirements and also provide direct measurement of radial velocity as a fourth dimension (4D). In this talk we present the latest results in the development of large scale, high performance coherent LiDAR FPAs enabled by comprehensive chipscale optoelectronic integration. An overview of performance of a 352x176 pixels two dimensional FM LiDAR FPA comprising over 0.6 million photonic components with all photonics and associated electronics components integrated on chip will be presented, as well as future development directions.

Biography

Remus Nicolaescu is the Co-founder and Managing Director of Pointcloud GmbH/Inc., a Zurich based technology company developing coherent 4D imaging solutions using silicon photonics. Prior to Pointcloud, he held executive roles with technology companies in the US, Europe and Asia. He started his career at Intel, where he performed pioneering work in silicon photonics topics, such as optical Raman amplifiers and lasers in silicon waveguides, and high-speed silicon photonics modulators. He obtained his Masters and Ph.D. in Physics from University of Bucharest and Texas A&M University respectively, and MBA from INSEAD.

References

From Semiconductors to Quantum: Infineon's Multi-Technology Approach

S. Luber
Senior Director Technology & Innovation
Infineon Technologies AG, Neubiberg, Germany

Abstract

Quantum computing holds significant potential to revolutionize the future of technology, and Infineon Technologies is contributing to this evolution through its developments in quantum hardware. This presentation will showcase Infineon's activities in superconducting circuits, semiconducting SiGe-based qubits, and ion trap technologies. Drawing on its expertise in semiconductor manufacturing and design, Infineon is addressing key challenges in scalability, integration, and reliability for quantum computing systems.

The session will explore how Infineon's components and modules contribute to the development of robust quantum computing systems across these three leading technology platforms. Emphasis will be placed on the holistic approach, which combines deep materials science knowledge, advanced process technologies, and collaboration within the quantum ecosystem. Join us to gain insight into how Infineon is shaping the future of computing.

Biography

Sebastian M. Luber holds a PhD in technical physics from the Walter Schottky Institute at the Technical University of Munich and is Senior Director for Technology & Innovation at Infineon Technologies AG. He coordinates Infineon's activities in the field of quantum technologies and acts as an advisor to the Management Board. Luber is involved in a variety of external committees and activities dealing with quantum technologies. Among others, he is member of the Program Committee for Quantum Technologies of the Federal Ministry of Education and Research, and active in QUTAC, the German Quantum Technology & Application Consortium. Previously, he held various positions in the company, including Sensor Technology Line Manager and Automotive Program Manager.

References

From Lab to Leadership - Europe's bet on Semiconductor Startups

M. Machold
Operational Director - Venture Lab
Quantum/Semicon
TUM Venture Labs, Venture Lab
Quantum/Semicon, Garching, Germany



Abstract

The semiconductor landscape is being redefined by emerging computing paradigms— from photonics to quantum sensing and quantum computing. Startups are the essential force, bringing radical, capital-efficient solutions to complex challenges.

This session will first highlight how TUM Venture Labs—Munich's deep-tech entrepreneurship hub—aims to accelerate the next wave of European semiconductor ventures by providing targeted domain expertise, infrastructure, and access to a global ecosystem.

We then showcase a key success story: QuantumDiamonds. They exemplify this disruption by introducing quantum sensor-based metrology using diamond NV centers to provide non-destructive 3D defect imaging deep within the complex architectures of modern chip packaging.

We will explore how this deep-tech innovation is critical for boosting yield and strengthening Europe's position. Finally, we'll hear impulse points on strategy and collaboration from Quantum Diamonds, offering the perspective of a cutting-edge European semicon startup.

Biography

Michael Machold is Operational Director at **TUM Venture Labs Quantum/Semicon**, where he is building the leading incubation program for founders in semiconductors, photonics, nanotech, and quantum technologies, actively driving Europe's deep-tech startup ecosystem. With over a decade of experience at Infineon Technologies, including serving as Director – Head of Product Management Automotive Microcontroller, Michael brings deep insights into the semiconductor industry.

Kevin Berghoff is the CEO of **QuantumDiamonds**. Previously, he worked at McKinsey in semiconductor and high-tech strategies and studied Business Administration in Cologne, Lisbon, and Munich. Under his leadership, QuantumDiamonds is working with leading global chip companies on the introduction of quantum sensor-based metrology for modern packaging technologies.

References

Digitalization in Semiconductor Manufacturing Supply Chain – Need of Global Collaboration

H. Gossner
Senior Principal Engineer
Intel, SiG, München, Germany



Abstract

Semiconductor-X introduces a secure and interoperable dataspace for the international semiconductor supply chain.

Demonstrating key use cases for planning, optimizing, regulatory reporting and enablement of new business models using digital twin technology.

Semiconductor-X is working with US and Asian partners to align the international standardization of digital twins and data space connectors for semiconductor supply chain usage.

Biography

Harald Gossner holds the position of a Senior Principal Engineer at Intel. He received his diploma degree in physics from Ludwig-Maximilians-University, Munich in 1990 and his PhD in electrical engineering from Universität der Bundeswehr, Munich in 1995. For 15 years he has worked on the development of electrostatic discharge (ESD) protection concepts with Siemens and Infineon Technologies. In 2011 he joined Intel leading the system ESD robustness development for Intel products.

He is the co-founder and co-chair of the Industry Council on ESD Target Levels representing more than 60 companies including all leading semiconductor manufacturers. He is President Emeritus of the EOS/ESD Association, Rome, NY, IEEE Fellow and editor of IEEE Electron Device Letters.

In his role as technology advisor, he is member of the industry advisory boards of the Bavarian Government and of several Fraunhofer institutes. He is part of the expert commission on AI of the German Economic Council. Since 2024 he is leading the project Semiconductor-X, coordinating the development of a dataspace for a resilient supply chain of semiconductors for Europe. He is also driving the build-up of a design ecosystem of innovative designs in digital leading edge technologies in Europe.

References